

注記(NOTES)  
 1. 使用材料 (MATERIAL)  
 ターミナル (TERMINAL): リン青銅  
 PHOSPHOR BRONZE  $\pm 0.2$   
 錫ビスマスメッキ 1. 0マイクロメートル以上  
 TIN-BISMUTH 1.0 MICROMETER MINIMUM  
 ニッケル下地 1. 0マイクロメートル以上  
 NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM  
 ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0  
 金具 (FITTING NAIL): リン青銅  
 PHOSPHOR BRONZE  $\pm 0.2$   
 錫メッキ 1. 0マイクロメートル以上  
 TIN 1.0 MICROMETER MINIMUM  
 ニッケル下地 1. 0マイクロメートル以上  
 NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM  
 ③ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)  
 ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L  
 に対し上方向 0.1MAX、下方向 0.15MAX、とする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L  
 UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.  
 ④ 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)  
 5. 本製品は 52689-\*\*\*40 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE 52689-\*\*\*40.

MODEL NO. 52689-\*\*\*49

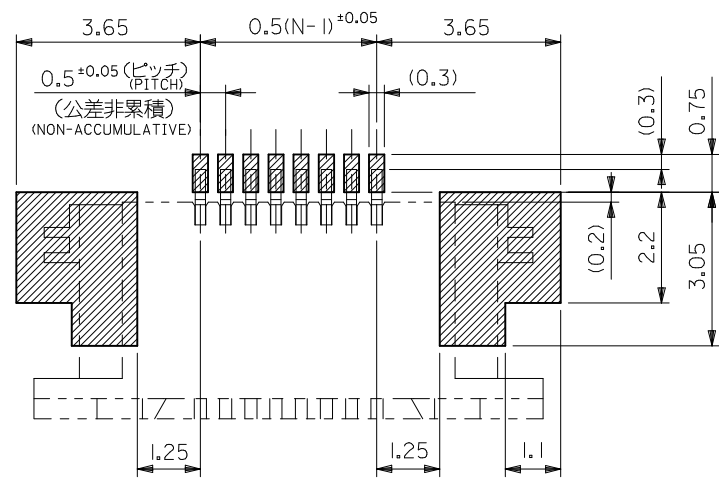
DESIGN UNITS METRIC THIRD ANGLE PROJECTION

0.5 FPC CONN NON ZIF  
 HSG ASSY FOR SMT(R/A)  
 -LEAD FREE-

**molex**

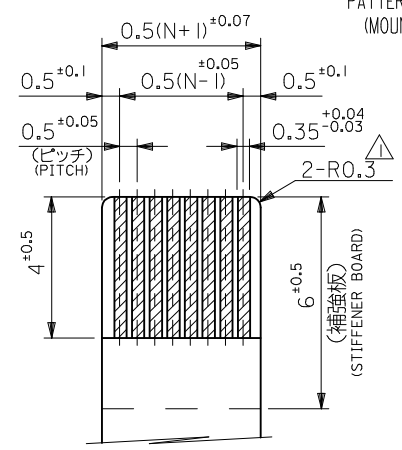
DOCUMENT NO. SD-52689-034 SHEET NO. 1 OF 2

GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
0.25 UNDER	UNDER	$\pm 0.03$	DRAWN BY	DATE	TITLE		
0.25 OVER	0.5 UNDER	$\pm 0.05$	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-		
0.5 OVER	1.0 UNDER	$\pm 0.1$	CHECKED BY	DATE			
1.0 OVER	10 UNDER	$\pm 0.2$	K. TOJO	'04/02/03			
10 OVER	30 UNDER	$\pm 0.25$	APPROVED BY	DATE			
30 OVER		$\pm 0.3$	M. SASAO	'04/02/03			
ANGULAR	$\pm 3^\circ$		MATERIAL NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE SHEET 2				
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

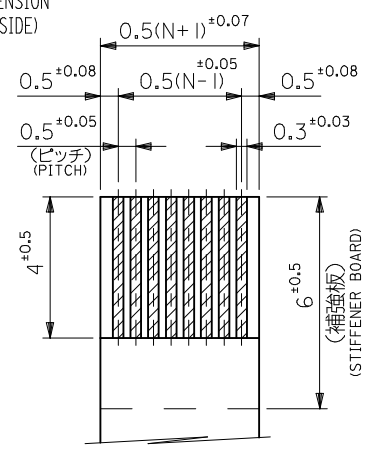


参考基板レイアウト  
(マウント面)

REFERENCE P.C. BOARD  
PATTERN DIMENSION  
(MOUNTING SIDE)



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.3±0.03)  
(THICKNESS: 0.3±0.03)



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.3±0.03)  
(THICKNESS: 0.3±0.03)

FPCについて:  
打抜き方向は導体側から補強板側を推奨致します。  
補強フィルム材質はポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。  
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

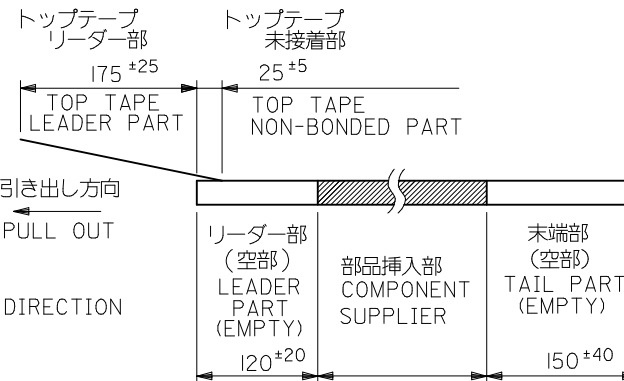
17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
MODEL NO.						ORDER No. オーダー番号		

REVISED EC NO: J2016-1029 DRWN: SKITAZAWA 2016/03/30 CHKD: APPR: TKSUJHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K. TOJO	DATE '04/02/03		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/02/03		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
10 OVER	30 UNDER	±0.25	SEE TABLE		SD-52689-034	2 OF 2	
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR		±3 °					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

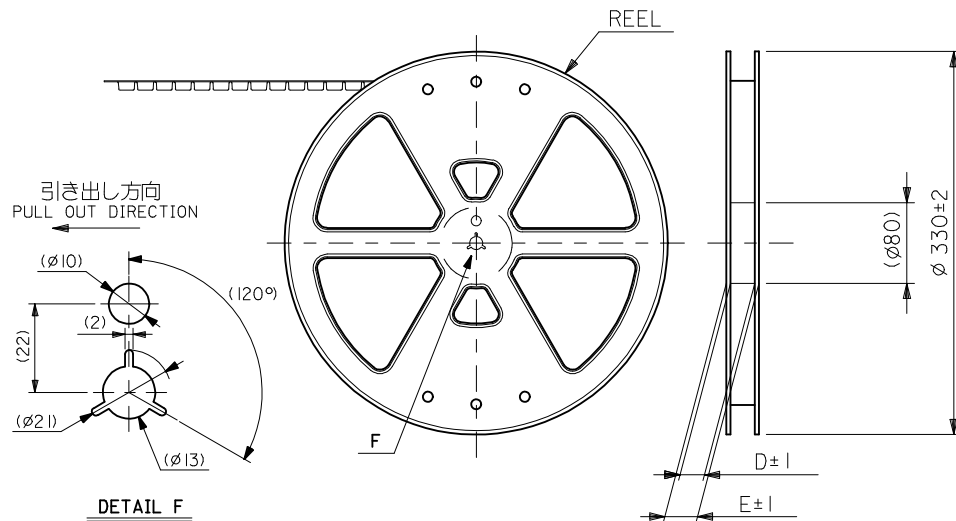
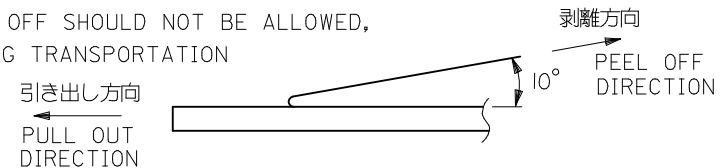
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。  
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール  
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)  
0.1~1.3N {10~130gf}  
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE  
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
PEEL OFF SHOULD NOT BE ALLOWED,  
DURING TRANSPORTATION



- 材料  
キャリアテープ：ポリプロピレン (PP)  
トップテープ：PET, PE, PEF  
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE  
TOP TAPE:PET,PE,PEF  
REEL:POLYSTYREN(PS)  
<RECYCLE MATERIAL CONTAINED>

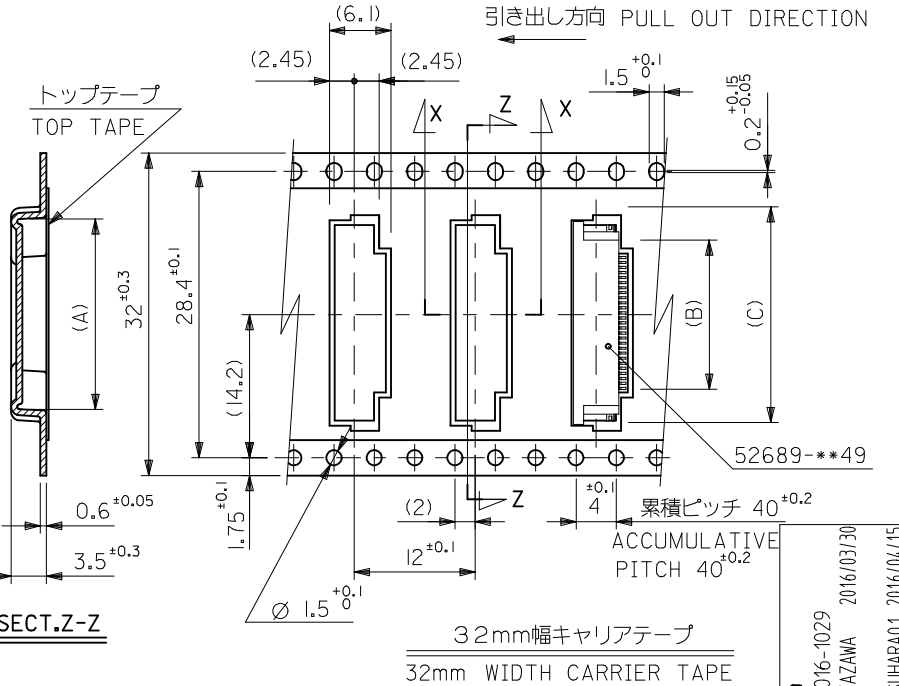
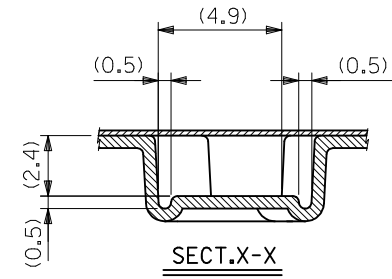
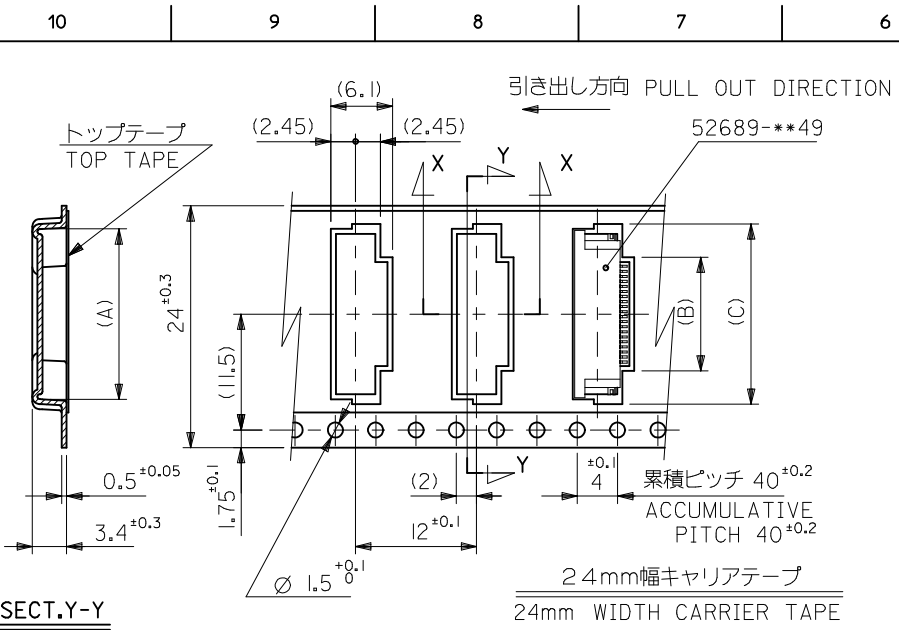
- 本製品は52689-\*\*\*93の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52689-\*\*\*93.

- FPCについて：  
打抜き方向は導体側から補強板側を推奨致します。  
補強フォルム材質はポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION :  
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

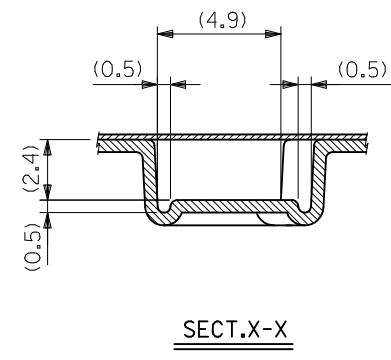
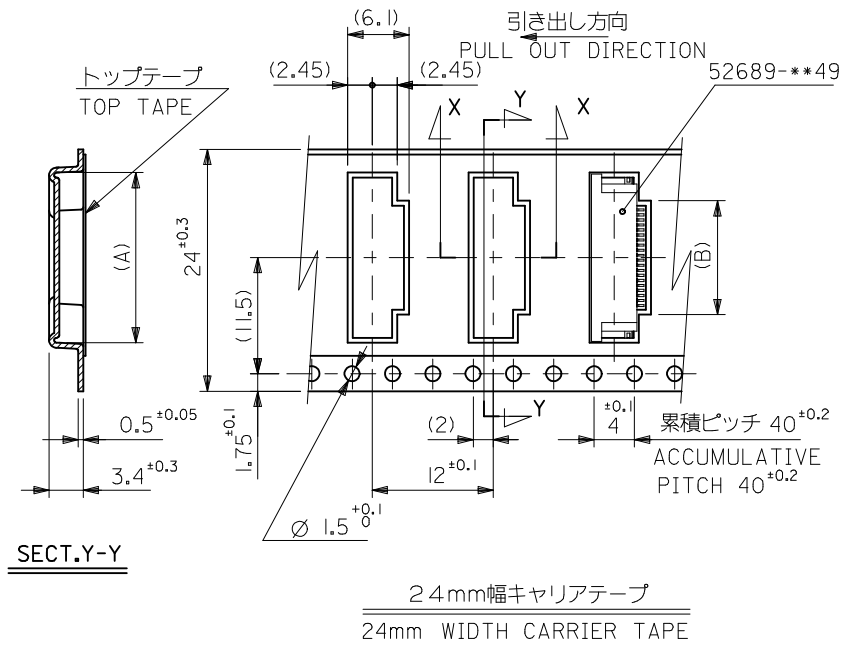
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO: J2016-1029 DRWN:SKITAZAWA 2016/03/30 CHKD: APPR:TKUJHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K.TOJO	DATE 2004/02/03		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M.SASAO	DATE 2004/02/03		
1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	SEE SHEET 2,3		SD-52689-035		1 OF 3
30 OVER		±0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	ANGULAR		±0.3				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						



32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30
24	29.4	25.4	17.4	10.8	16.4	-2087	20
			16.4	9.8	15.4	-1887	18
			15.4	8.8	14.4	-1687	16
			14.9	8.3	13.9	-1587	15
			12.4	5.8	11.4	-1087	10
			11.4	4.8	10.4	-0887	8
			10.9	4.3	9.9	-0787	7
9.9	3.3	8.9	52689 -0587	5			

REVISED	EC NO: J2016-1029	DRWN:SKITAZAWA	2016/03/30	CHKD:	APPR:KUSUHARA01	2016/04/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	0.25 UNDER UNDER ±0.03	0.25 OVER 0.5 UNDER ±0.05	0.5 OVER 1.0 UNDER ±0.1	1.0 OVER 10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MODEL NO. 52689-**-87	CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	種数 CIRCUIT		
DIMENSION STYLE																		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION					
MM ONLY																		---		METRIC		☉					
DRAWN BY H.KAWABATA																		DATE 2004/02/03		TITLE		0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-					
CHECKED BY K.TOJO																		DATE 2004/02/03		APPROVED BY M.SASAO		DATE 2004/02/03					
MATERIAL NO.																		DOCUMENT NO.		SEE TABLE		SD-52689-035					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																											



24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

52689-***87	24	29.4	25.4	11.8	17.4	52689-2287	22
MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2016-1029 DRWN:SKITAZAWA 2016/03/30 CHKD: APPR:KUSUHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	<b>molex</b> DOCUMENT NO. SD-52689-035 SHEET NO. 3 OF 3		
	1.0 OVER	10 UNDER	±0.2	K.TOJO	2004/02/03			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SEE TABLE			
30 OVER		±0.3	M.SASAO	2004/02/03	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	ANGULAR	±3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					